Power MOSFET

60 V, 1.2 m Ω , 287 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage	Gate-to-Source Voltage			±20	V
Continuous Drain	Steady	T _C = 25°C	I _D	287	Α
Current R _{0JC} (Notes 1, 3)		T _C = 100°C		203	
Power Dissipation	State	T _C = 25°C	P _D	200	W
R _{θJC} (Note 1)		T _C = 100°C		100	
Continuous Drain		T _A = 25°C	I _D	40	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady	T _A = 100°C		28	
Power Dissipation	State	T _A = 25°C	P _D	3.9	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.9	
Pulsed Drain Current	$T_A = 25$	°C, t _p = 10 μs	I _{DM}	900	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			IS	203	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 22 A)			E _{AS}	776	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.75	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	

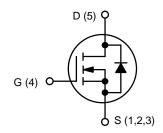
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface–mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



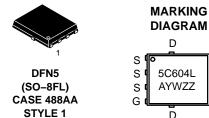
ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
60 V	1.2 mΩ @ 10 V	287 A	
00 V	1.7 mΩ @ 4.5 V	201 A	



N-CHANNEL MOSFET



D

D

5C604L = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS	•						•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				22.9		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	T _J = 25°C			10		
		V _{DS} = 60 V	T _J = 125°C			250	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS}$	_S = 20 V			100	nA	
ON CHARACTERISTICS (Note 4)						•	•	
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	1.2		2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.9		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		0.93	1.2		
		V _{GS} = 4.5 V	I _D = 50 A		1.25	1.7	mΩ	
Forward Transconductance	9FS	V _{DS} = 15 V, I _E	o = 50 A		180		S	
CHARGES, CAPACITANCES & GATE R	ESISTANCE							
Input Capacitance	C _{ISS}				8900			
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1 MH	Iz, V _{DS} = 25 V		3750		pF	
Reverse Transfer Capacitance	C _{RSS}				40		1	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V}; I_D = 50 \text{ A}$			52			
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 30 V; I _D = 50 A			120		1	
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V}; I_D = 50 \text{ A}$			6.4		nC	
Gate-to-Source Charge	Q _{GS}				21.4			
Gate-to-Drain Charge	Q_{GD}				12.7			
Plateau Voltage	V_{GP}				2.8		V	
SWITCHING CHARACTERISTICS (Note	5)					•	•	
Turn-On Delay Time	t _{d(ON)}				21.8			
Rise Time	t _r	V _{GS} = 4.5 V, V _F	ns = 30 V,		79.1			
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V},$ $I_{D} = 50 \text{ A}, R_{G} = 2.5 \Omega$			57.8		ns	
Fall Time	t _f				81.3			
DRAIN-SOURCE DIODE CHARACTERI	STICS					•	•	
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.78	1.2	.,	
		$I_S = 50 \text{ A}$	T _J = 125°C		0.64		V	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 50 \text{ A}$			98		ns	
Charge Time	ta				45			
Discharge Time	t _b				53			
Reverse Recovery Charge	Q_{RR}				190		nC	

- 4. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

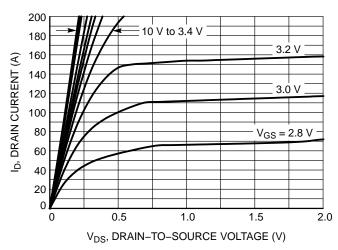


Figure 1. On-Region Characteristics

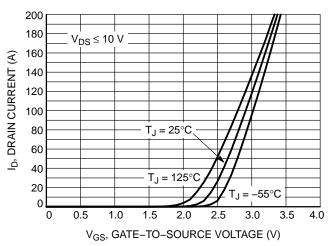


Figure 2. Transfer Characteristics

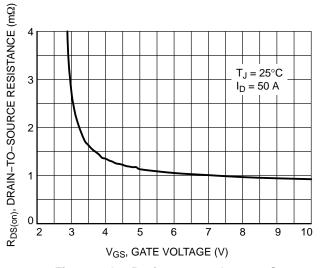


Figure 3. On–Resistance vs. Gate–to–Source Voltage

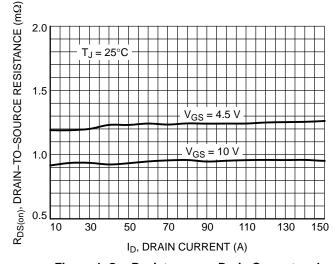


Figure 4. On–Resistance vs. Drain Current and Gate Voltage

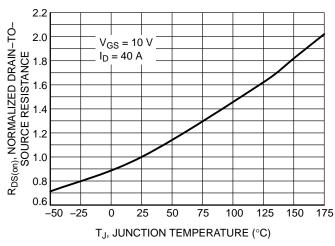


Figure 5. On–Resistance Variation with Temperature

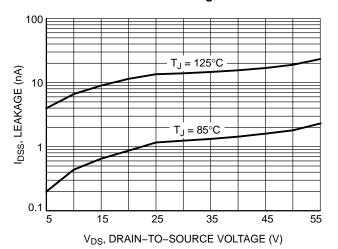
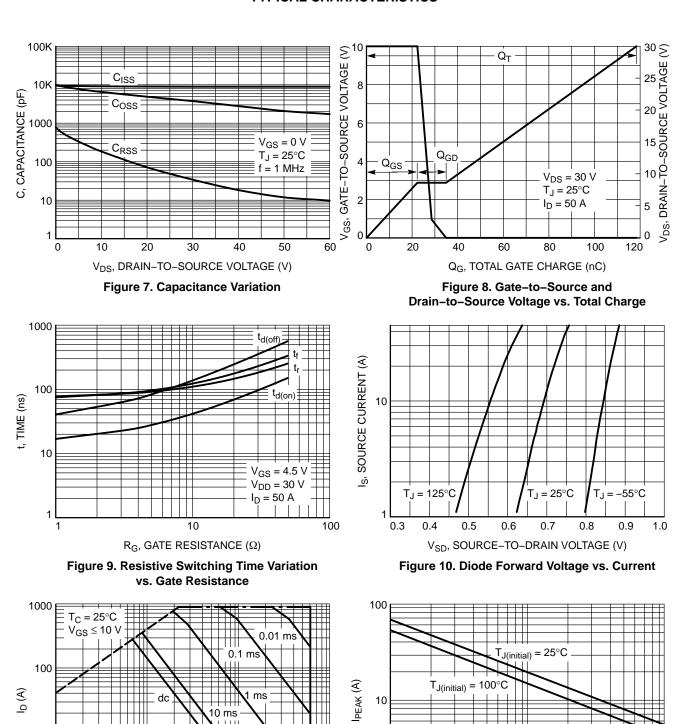


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS



 $\label{eq:VDS} V_{DS}\left(V\right)$ Figure 11. Safe Operating Area

10

R_{DS(on)} Limit Thermal Limit Package Limit

10

0.1

TIME IN AVALANCHE (s) Figure 12. I_{PEAK} vs. Time in Avalanche

1E-03

1E-02

100

1E-04

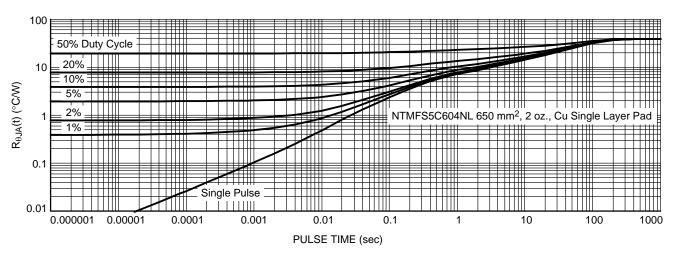


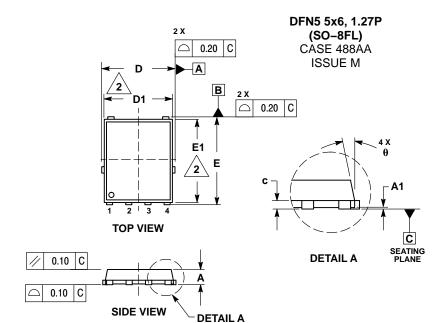
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C604NLT1G	5C604L	DFN5 (Pb-Free)	1500 / Tape & Reel
NTMFS5C604NLT3G	5C604L	DFN5 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



NOTES:

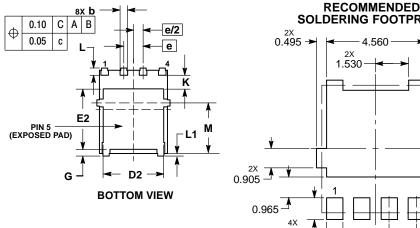
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS.

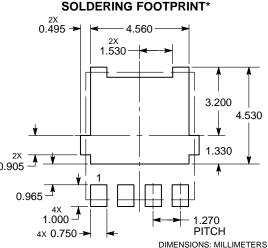
	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
M	3.00	3.40	3.80	
θ	0 °		12 °	

STYLE 1:

PIN 1. SOURCE

- SOURCE
- SOURCE GATE
- DRAIN





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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